

High Current FET Driver

FEATURES

- Totem Pole Output with 6A Source/Sink Drive
- 3ns Delay
- 20ns Rise and Fall Time into 2.2nF
- 8ns Rise and Fall Time into 30nF
- 4.7V to 18V Operation
- Inverting and Non-Inverting Outputs
- Under-Voltage Lockout with Hysteresis
- Thermal Shutdown Protection
- MINIDIP and Power Packages

DESCRIPTION

The UC1710 family of FET drivers is made with a high-speed Schottky process to interface between low-level control functions and very high-power switching devices-particularly power MOSFET's. These devices accept low-current digital inputs to activate a high-current, totem pole output which can source or sink a minimum of 6A.

Supply voltages for both V_{IN} and V_C can independently range from 4.7V to 18V. These devices also feature under-voltage lockout with hysteresis.

The UC1710 is packaged in an 8-pin hermetically sealed dual in-line package for -55°C to $+125^{\circ}\text{C}$ operation. The UC2710 and UC3710 are specified for a temperature range of -40°C to $+85^{\circ}\text{C}$ and 0°C to $+70^{\circ}\text{C}$ respectively and are available in either an 8-pin plastic dual in-line or a 5-pin, TO-220 package. Surface mount devices are also available.

ORDERING INFORMATION

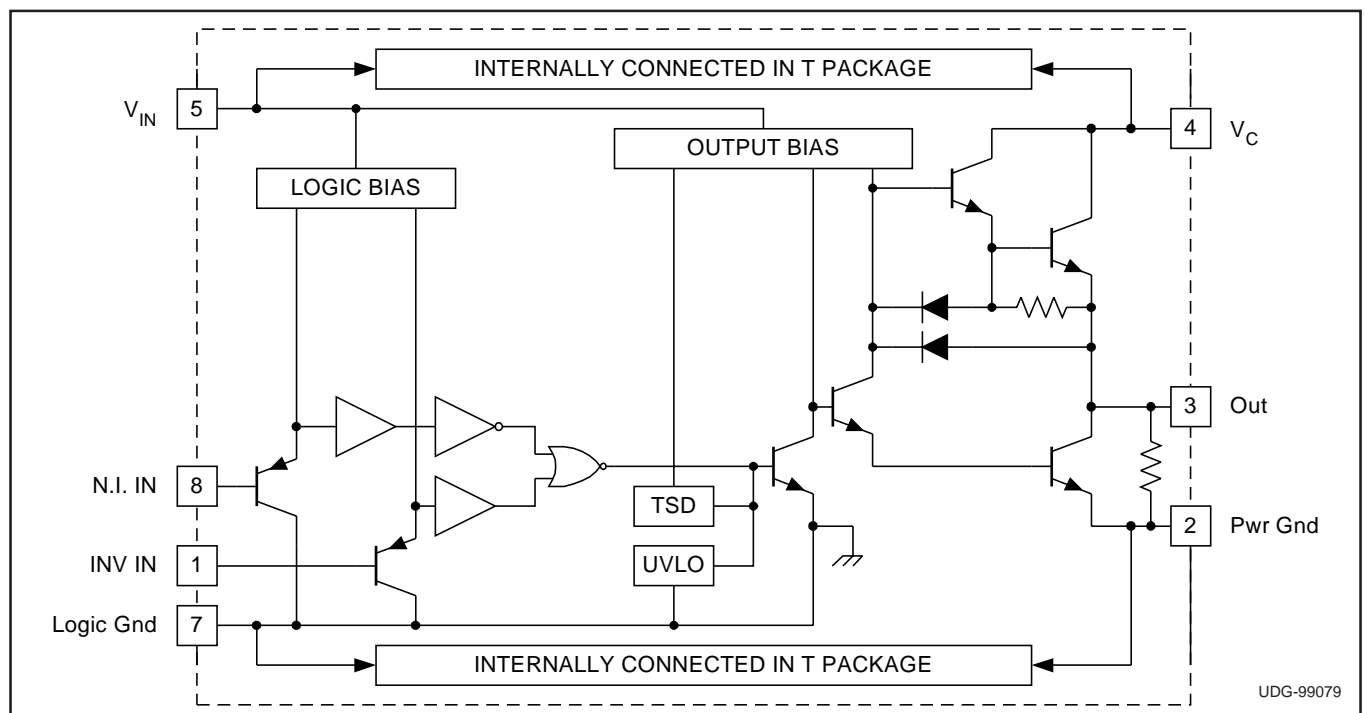
	TEMPERATURE RANGE	PACKAGE
UC1710J	-55°C to $+125^{\circ}\text{C}$	8 pin CDIP
UC2710DW	-40°C to $+85^{\circ}\text{C}$	16 pin SOIC-wide
UC2710J		8 pin CDIP
UC2710N		8 pin PDIP
UC2710T		5 pin TO220
UC3710DW	0°C to $+70^{\circ}\text{C}$	16 pin SOIC-wide
UC3710N		8 pin PDIP
UC3710T		5 pin TO220

TRUTH TABLE

INV	N.I.	Out
H	H	L
L	H	H
H	L	L
L	L	L

$\overline{\text{OUT}} = \overline{\text{INV}} \text{ and } \overline{\text{N.I.}}$
 $\overline{\text{OUT}} = \text{INV or N.I.}$

BLOCK DIAGRAM



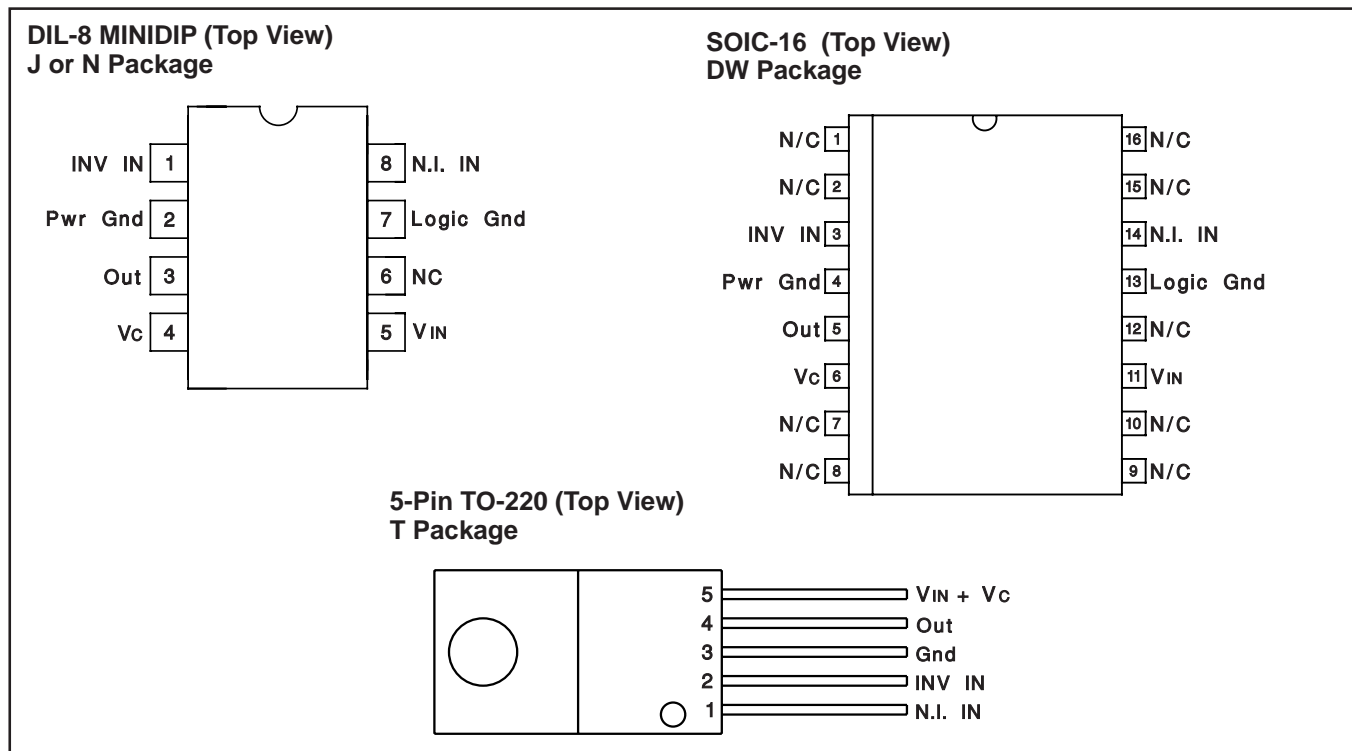
ABSOLUTE MAXIMUM RATINGS

	N-Package	J-Package	T-Package
Supply Voltage, V_{in}	20V	20V	20V
Collector Supply Voltage, V_C	20V	20V	20V
Operating Voltage	18V	18V	18V
Output Current (Source or Sink)			
Steady-State	$\pm 500\text{mA}$	$\pm 500\text{mA}$	$\pm 1\text{A}$
Digital Inputs	$-0.3\text{V} - V_{IN}$	$-0.3\text{V} - V_{IN}$	$-0.3\text{V} - V_{IN}$
Power Dissipation at $T_a=25^\circ\text{C}$	1W	1W	3W
Power Dissipation at T (Case) = 25°C	2W	2W	25W
Operating Junction Temperature	-55°C to $+150^\circ\text{C}$	-55°C to $+150^\circ\text{C}$	-55°C to $+150^\circ\text{C}$
Storage Temperature	-65°C to $+150^\circ\text{C}$	-65°C to $+150^\circ\text{C}$	-65°C to $+150^\circ\text{C}$
Lead Temperature (Soldering, 10 seconds)	300°C	300°C	300°C

Note 1: All currents are positive into, negative out of the specified terminal.

Note 2: Consult Unitrode Integrated Circuits databook for information regarding thermal specifications and limitations of packages.

CONNECTION DIAGRAMS



ELECTRICAL CHARACTERISTICS: Unless otherwise stated, these specifications apply for $V_{IN} = V_C = 15\text{V}$, No load, $T_A = T_J$.

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
V_{IN} Supply Current	$V_{IN}=18\text{V}, V_C=18\text{V}, \text{Output Low}$		26	35	mA
	$V_{IN}=18\text{V}, V_C=18\text{V}, \text{Output High}$		21	30	mA
V_C Supply Current	$V_{IN}=18\text{V}, V_C=18\text{V}, \text{Output Low}$		1.5	5.0	mA
	$V_{IN}=18\text{V}, V_C=18\text{V}, \text{Output High}$		5.0	8	mA
UVLO Threshold	V_{IN} High to Low	3.8	4.1	4.4	V
	V_{IN} Low to High	4.1	4.4	4.8	V

ELECTRICAL CHARACTERISTICS: Unless otherwise stated, these specifications apply for $V_{IN} = V_C = 15V$, No load, $T_A = T_J$.

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
UVLO Threshold Hysteresis		0.1	0.3	0.5	V
Digital Input Low Level				0.8	V
Digital Input High Level		2.0			V
Digital Input Current	Digital Input = 0.0V	-70	-4.0		μA
Output High Sat., $V_C - V_O$	$I_O = -100mA$		1.35	2.2	V
	$I_O = -6A$		3.2	4.5	V
Output Low Sat., V_O	$I_O = 100mA$		0.25	0.6	V
	$I_O = 6A$		3.4	4.5	V
Thermal Shutdown			165		$^{\circ}C$
From Inv., Input to Output (Note 3, 4):					
Rise Time Delay	CL = 0		35	70	ns
	CL = 2.2nF		35	70	ns
	CL = 30nF		35	70	ns
10% to 90% Rise	CL = 0		20	40	ns
	CL = 2.2nF		25	40	ns
	CL = 30nF		85	150	ns
Fall Time Delay	CL = 0		35	70	ns
	CL = 2.2nF		35	70	ns
	CL = 30nF		35	80	ns
90% to 10% Fall	CL = 0		15	40	ns
	CL = 2.2nF		20	40	ns
	CL = 30nF		85	150	ns
From N.I. Input to Output (Note 3,4):					
Rise Time Delay	CL = 0		35	70	ns
	CL = 2.2nF		35	70	ns
	CL = 30nF		35	70	ns
10% to 90% Rise	CL = 0		20	40	ns
	CL = 2.2nF		25	40	ns
	CL = 30nF		85	150	ns
Fall Time Delay	CL = 0		35	70	ns
	CL = 2.2nF		35	70	ns
	CL = 30nF		35	80	ns
90% to 10% Fall	CL = 0		15	40	ns
	CL = 2.2nF		20	50	ns
	CL = 30nF		85	150	ns
Total Supply Current at 200kHz Input Switching Frequency	$T_A = 25^{\circ}C$ (Note 5) CL = 0		30	40	mA

Note: 3. Delay measured from 50% input change to 10% output change.

Note: 4. Those parameters with CL = 30nF are not tested in production.

Note: 5. Inv. Input pulsed at 50% duty cycle with N.I. Input = 3V. or N.I. Input pulsed at 50% duty cycle with Inv. Input = 0V.

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